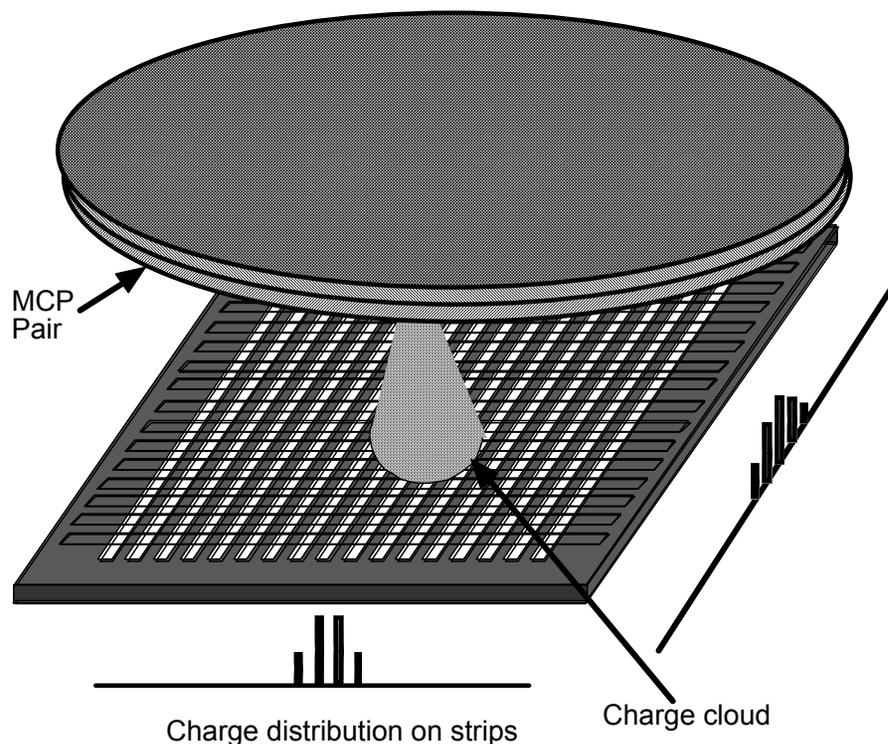




Detector configuration

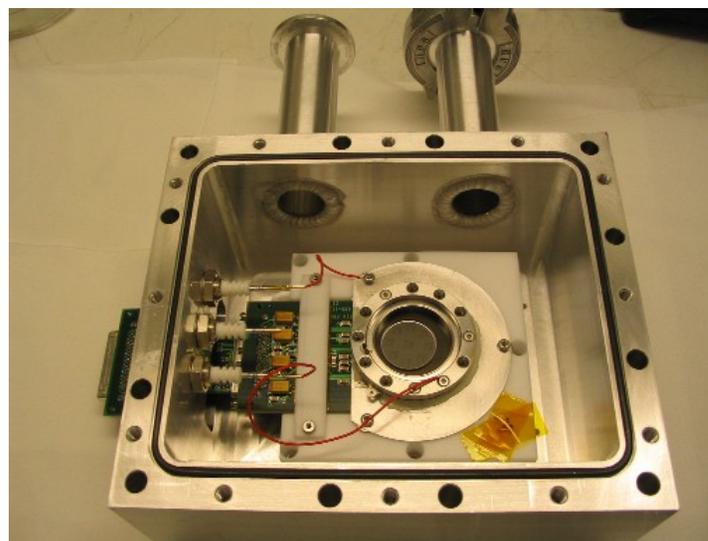
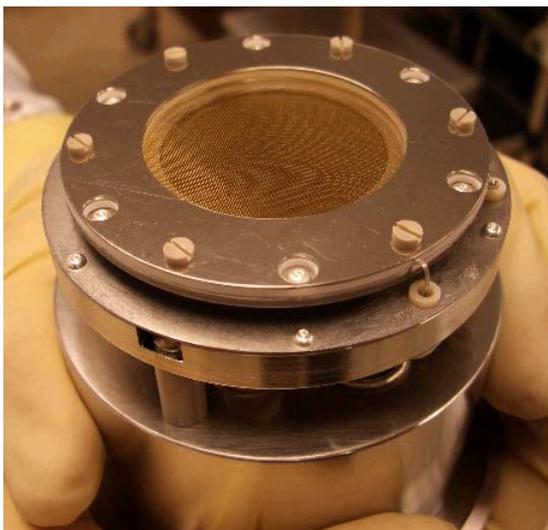


Schematic of an MCP detector

- Photon/ion/atom/neutron counting
- XY coordinates ($<20 \mu\text{m}$) and timing ($<130 \text{ps}$) information for each registered particle
- Selective detection of ions, electrons, photons
- Count rate \sim MHz with 10% dead time
- No dark/readout noise!



Detector hardware implementations

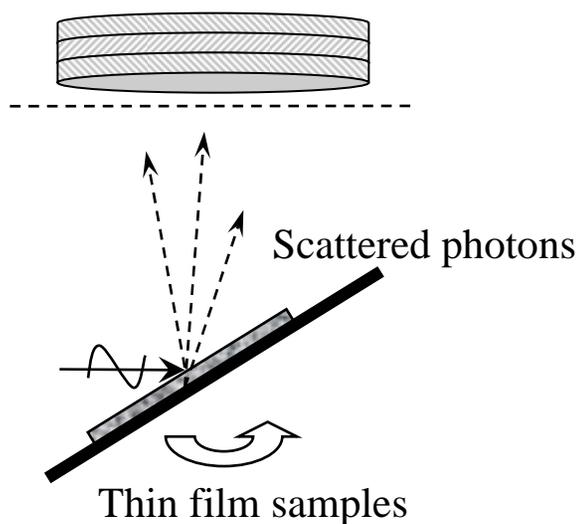




Experimental setup

2D Imaging +
time for each
detected photon

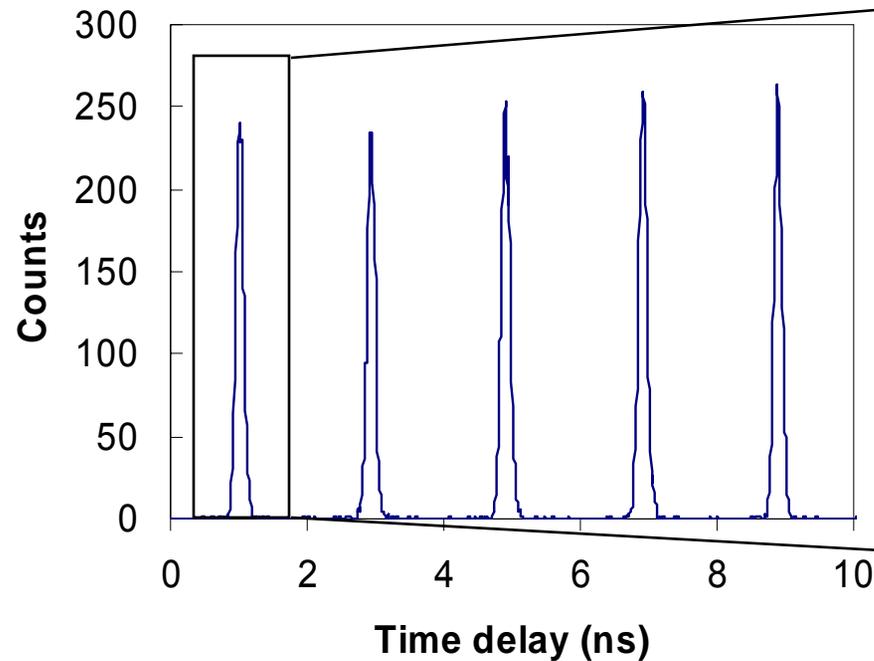

Synchrotron generated
photon pulses
~ 70 ps wide, 2 ns apart



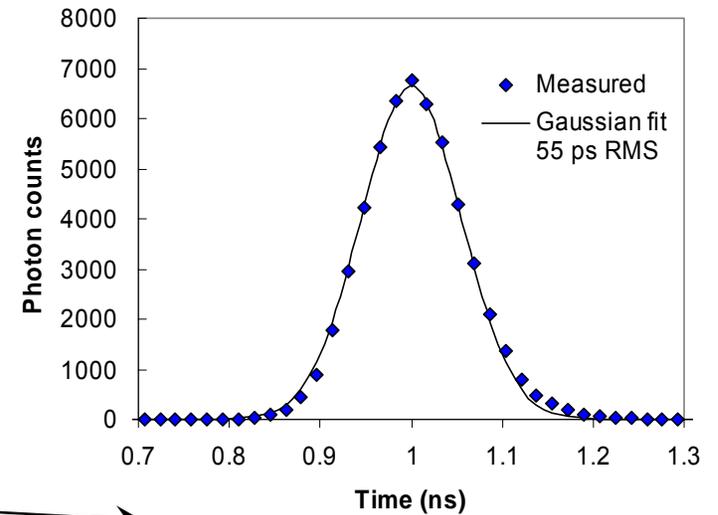


Timing resolution

Elastically scattered photons



Timing accuracy 55 ps RMS
(130 FWHM)

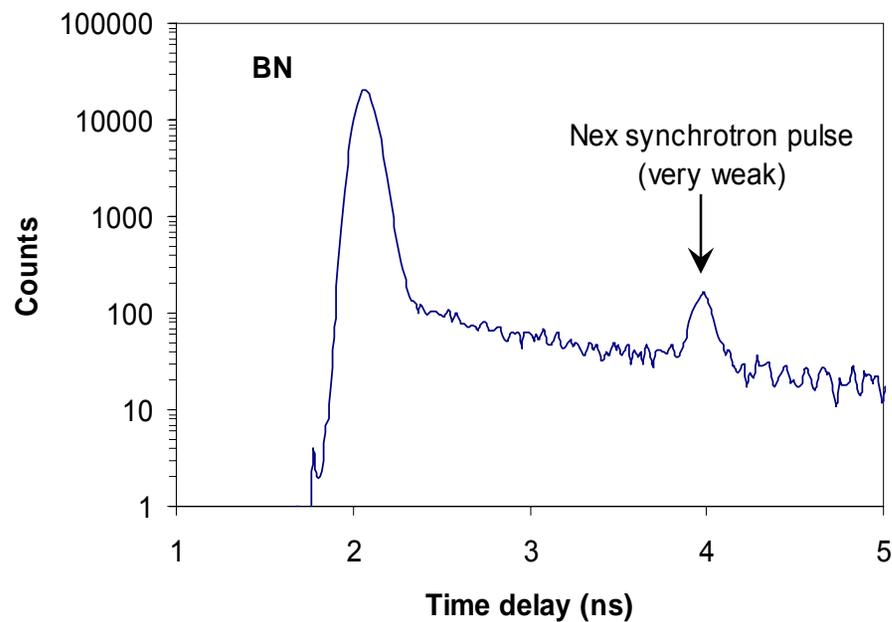
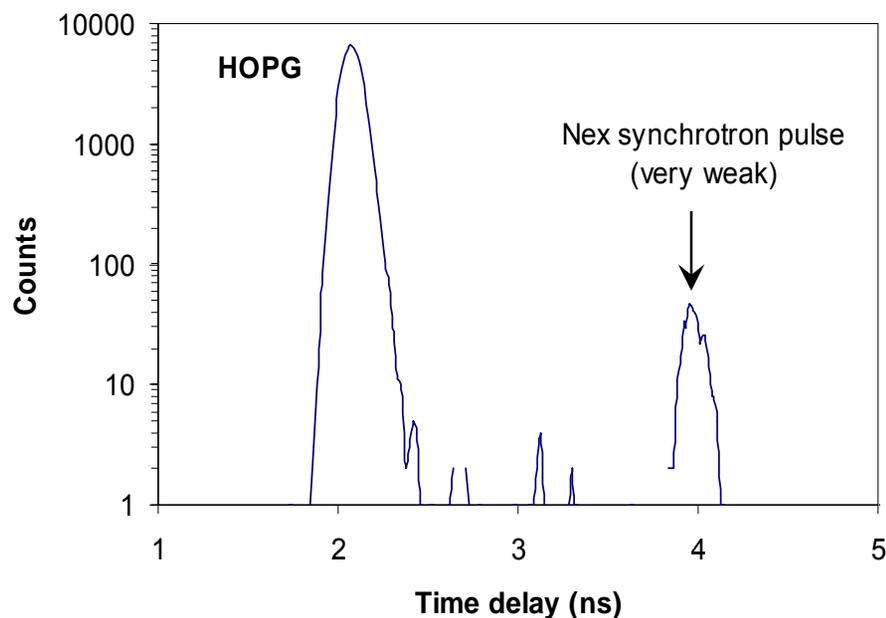




Time histograms for different films

Only elastic scattering

Both elastic and inelastic scattering are present



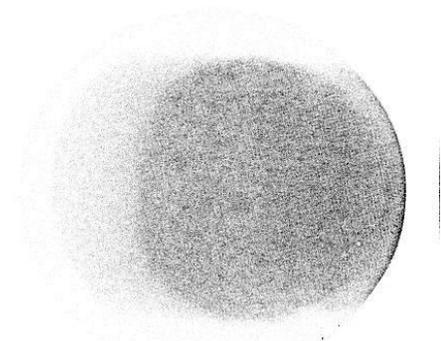
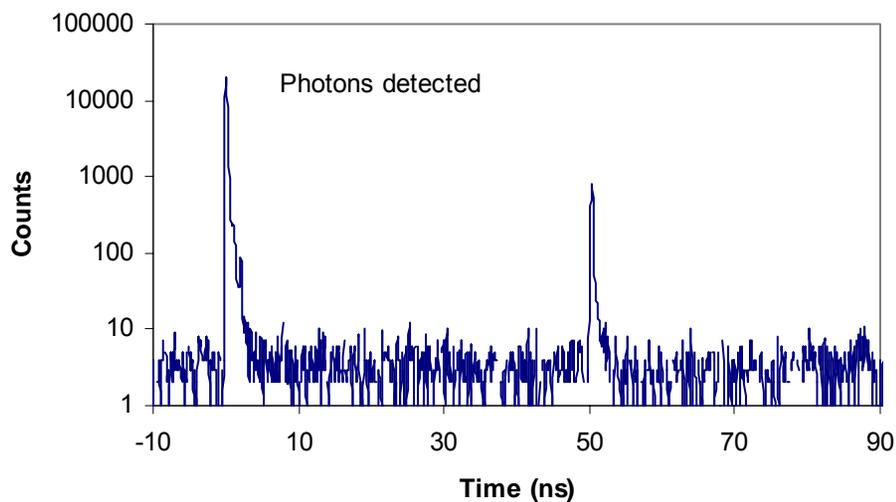
A. S. Tremsin, et al., IEEE Trans. Nucl. Sci. 54 (2007) 706.

SLAC, December 9, 2009

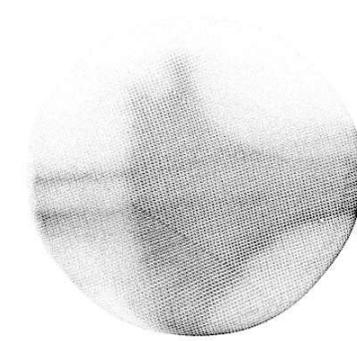
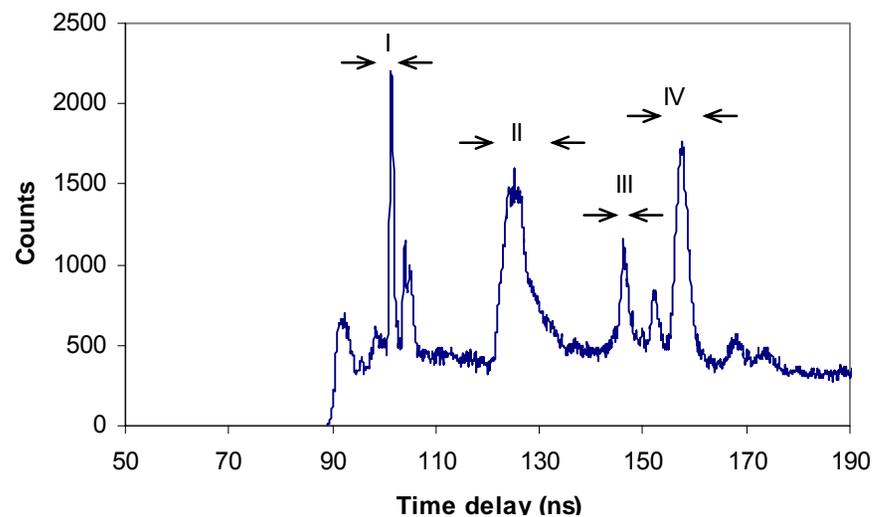


Time histograms & images: photons vs. electrons

Photons detected,
electrons repelled by input mesh



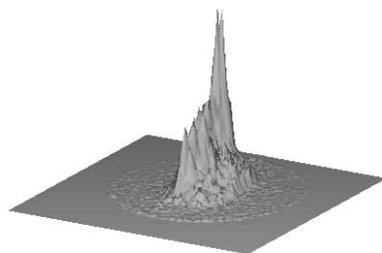
Time window selected for
only electron detection



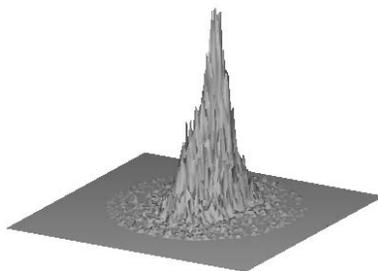
A. S. Tremsin, et al., Nucl. Instr. Meth. A 580 (2007) 853.



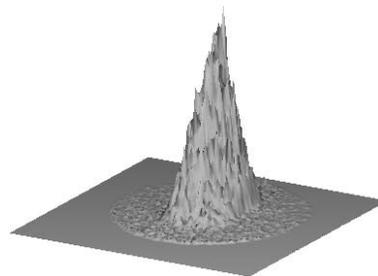
Images: electrons from different peaks



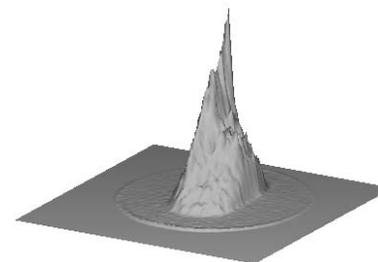
Only region I



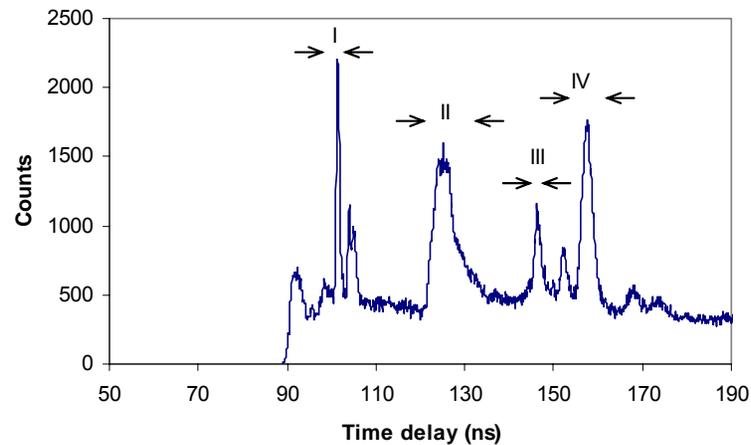
Only region II



Only region III



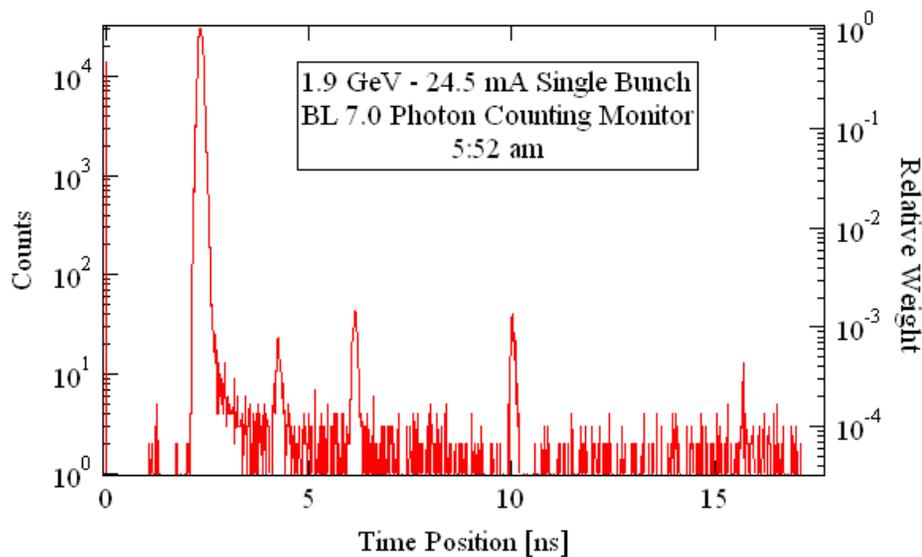
Entire histogram



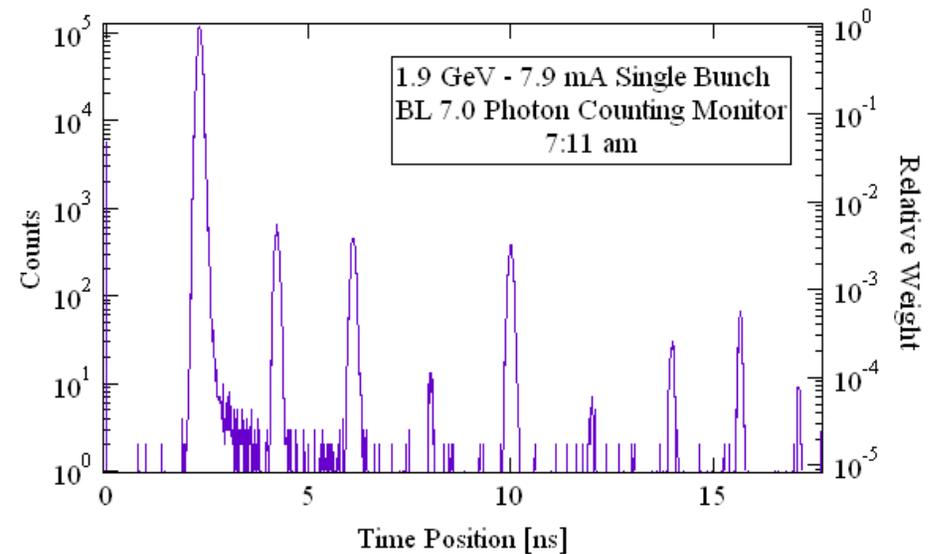


Synchrotron bunch diffusion

Bunch population after injection



Bunch population ~76 min later

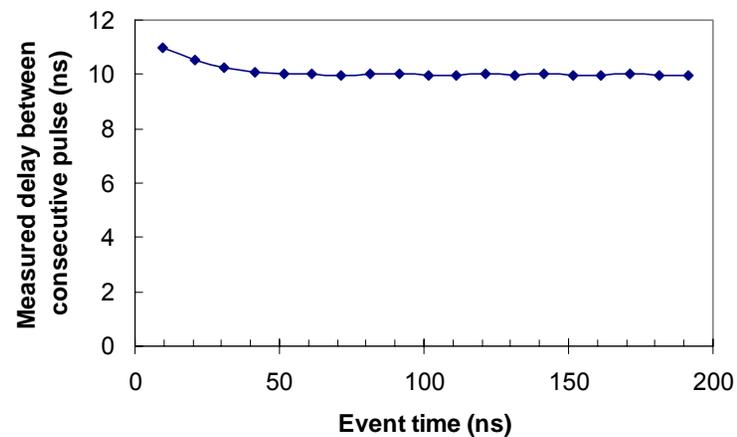
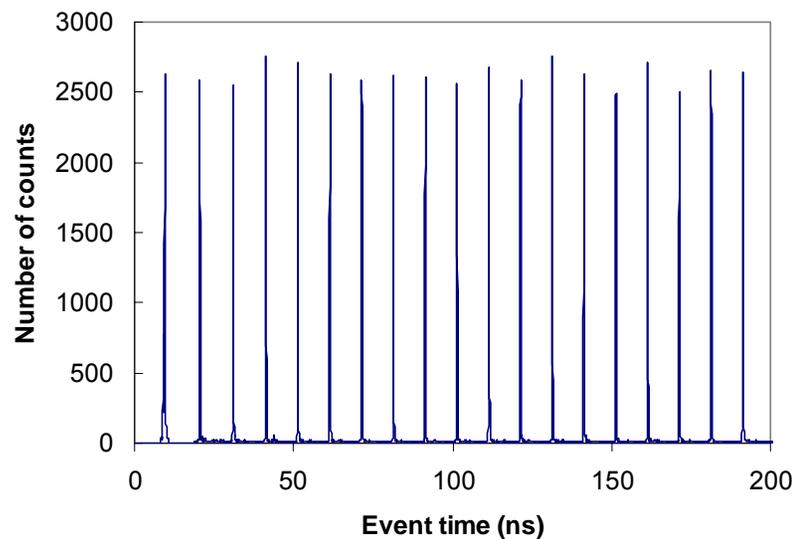


Diffusion of electrons between the adjacent bunches can be studied with the detection system

W. E. Byrne, C.-W. Chiu, J. Guo, F. Sannibale, J.S. Hull, O.H.W. Siegmund, A. S. Tremsin, J.V. Vallerga
Proceedings EPAC'06, Edinburgh, June 2006



Linearity of measured timing

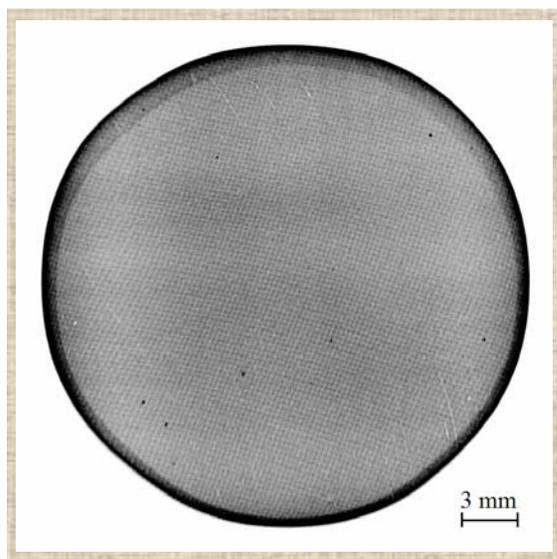


Measured timing histogram of electron pulses separated by 10 ns.

A. S. Tremsin, et al., Nucl. Instr. Meth. A 582 (2007) 168.



Spatial resolution: photons and electrons

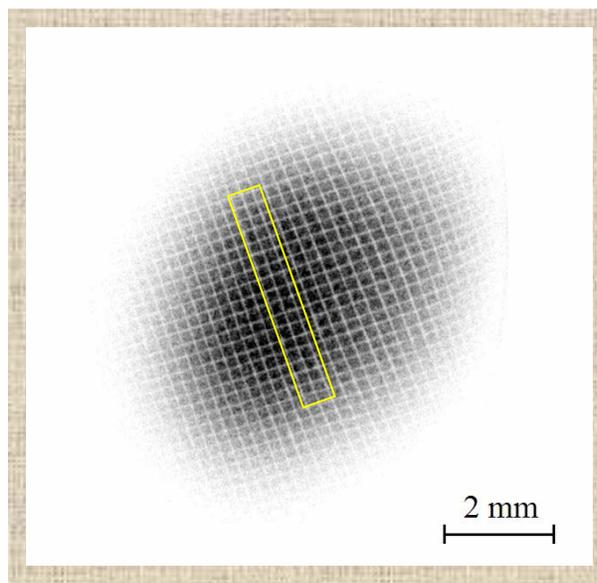


Photon image

Full field illumination

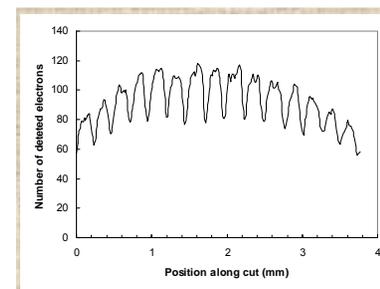
25 mm active area

Mesh with 250 μm rectangular cells



Electrons imaged

25 μm wires on 250 μm grid resolved



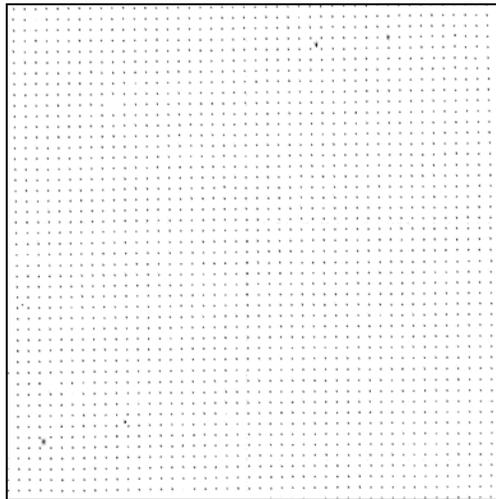
Cross section of electron image

25 μm wires are resolved

A. S. Tremsin, et al., Nucl. Instr. Meth. A 582 (2007) 168.

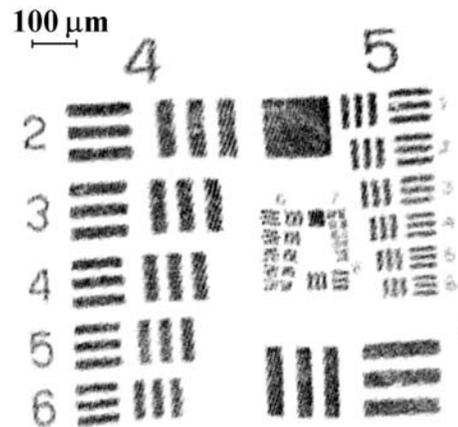


Spatial resolution of MCP detectors



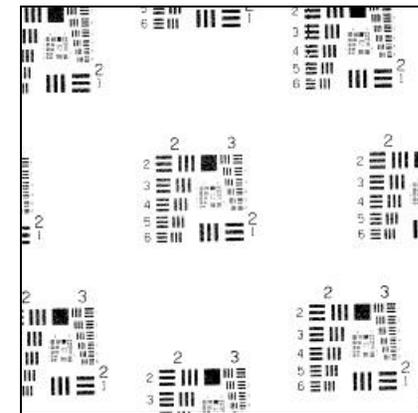
•XDL readout

- Very linear images
- Resolutions $\sim 25\mu\text{m}$ FWHM
- Large Formats (10cm x 10cm)
- Event rates ~ 0.5 MHz



•XS readout

- Very high resolution
- $\sim 12\mu\text{m}$ FWHM @ < 100 kHz
- $\sim 20\mu\text{m}$ FWHM @ few MHz



•CMOS readout

- Resolution $\sim 55\mu\text{m}$ FWHM
- Very high event rates > 1 GHz



MCP thermal runaway

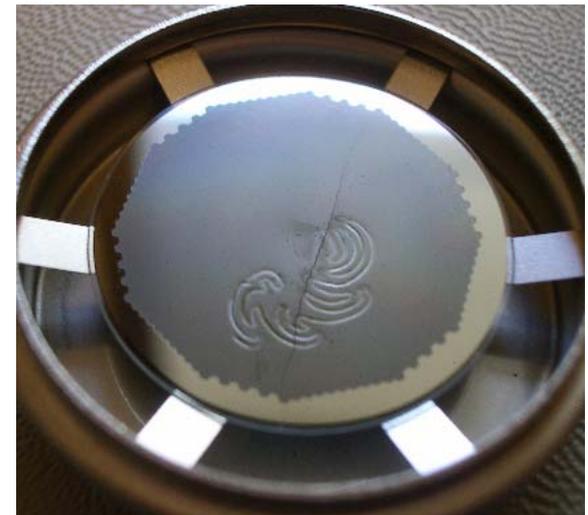
$$R_{MCP}(T_{MCP}, V_{MCP}) = R_0[1 - \alpha_v V_{MCP}] \exp\{-\beta_T(T_{MCP} - T_0)\}, \quad (1) \quad \alpha_T = 0.015 \text{ C}^{-1}$$

where R_0 is the resistance of MCP measured at $V_{MCP} = 0$ V and temperature $T_{MCP} = T_0$.

Stable operation when $Q_{joule} = Q_{rad} + Q_{cond}$.

$$Q_{Rad} = \frac{\pi \cdot D_0^2}{4} \cdot \sigma \cdot \epsilon \cdot (T_{MCP}^4 - T_A^4) \quad \epsilon \text{ the effective thermal emittance } (\epsilon=0.4)$$

heat dissipation from the MCP of only $0.015 \text{ W} \cdot \text{cm}^{-2}$ for $T_{MCP} = 70 \text{ }^\circ\text{C}$



A.S. Tremsin et al., Proc. SPIE **2808** (1996) pp.86-97.
A.S. Tremsin et al., Nucl. Instr.Meth. **379** (1996) pp.139-151.



Thermal Stability of MCPs

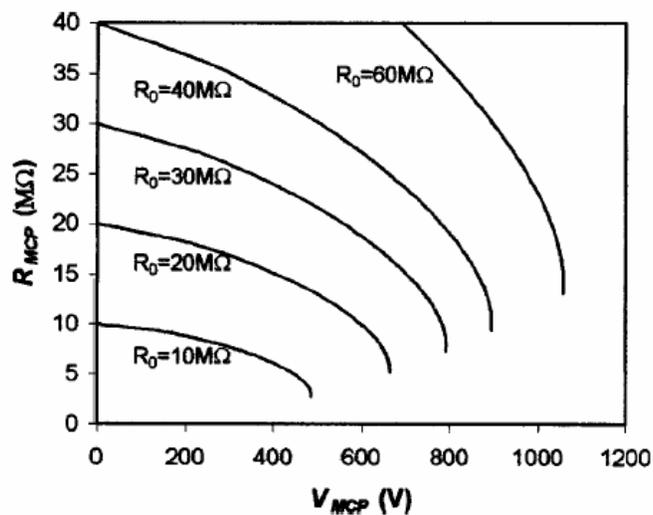


FIG. 6. Calculated resistance of a 40:1 L/D 25 mm diam silica MCP with 6 μm pores (mounted in a chevron stack) as a function of MCP bias V_{MCP} for different values of initial resistance R_0 . The initial resistance determines the maximum voltage, which can be applied to the MCP without inducing a thermal runaway.

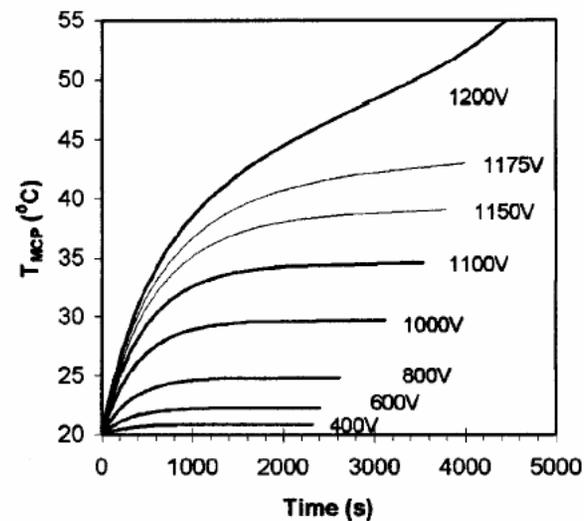
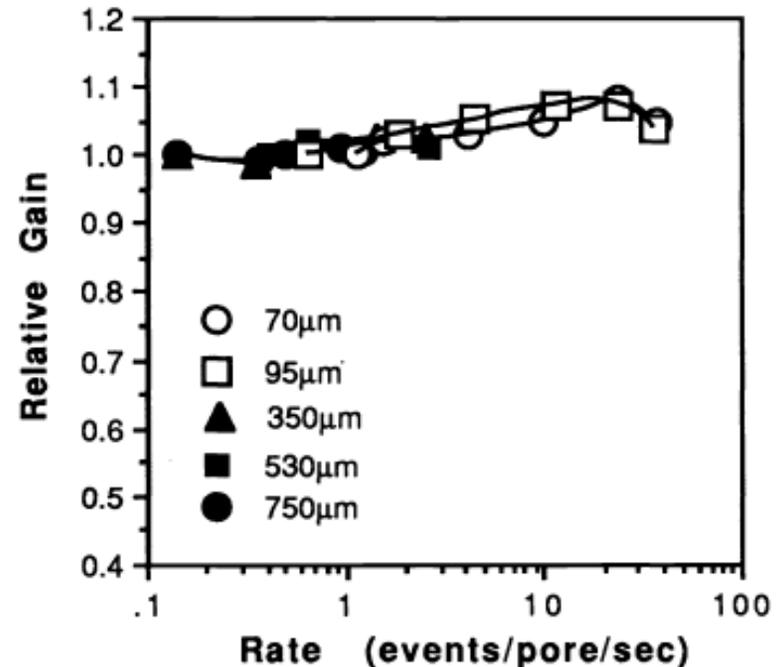
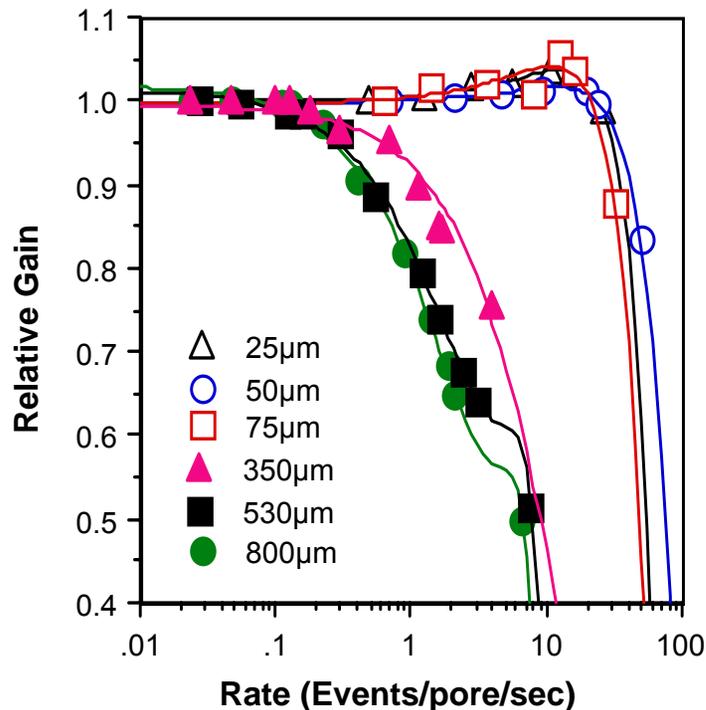


FIG. 7. Calculated temperature of silica MCP as a function of time after V_{MCP} is increased from 0 to a given voltage, indicated on the graph. MCP parameters are as in Fig. 2. For voltages below ~ 800 V the MCP reaches the thermal equilibrium in a few minutes.



Count rate limitation per illuminated area

Gain drop as a function of event rate for six different sized holes illuminated with 2537Å light. 60mm MCP Z stack.



$R = 600 \text{ M}\Omega/\text{cm}^2$, initial gain $\approx 1 \times 10^7$.

$R = 120 \text{ M}\Omega/\text{cm}^2$, initial gain $\approx 3 \times 10^6$.

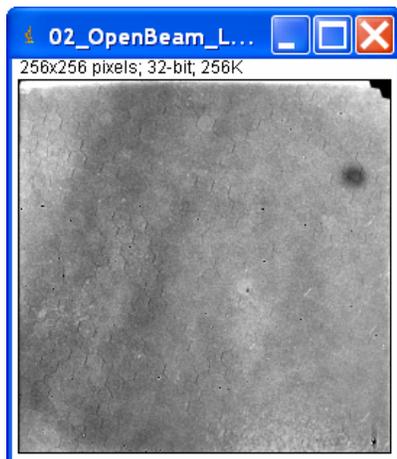
**Count rate limitation is dependent on the area illuminated:
larger area can sustain less counts per pore!**

O.H.W. Siegmund and Joseph M. Stock, Proc. SPIE 1549, 81 (1991)

SLAC, December 9, 2009



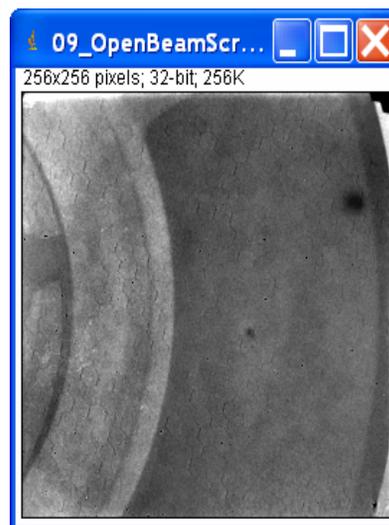
MCP gain reduction effect: ageing under irradiation



Uniform flat field image



Long integration image
Gain $\sim 10^5$
Rate > 10 MHz/cm²
Accumulated dose ~ 0.01 C/cm²



Almost uniform flat field illumination

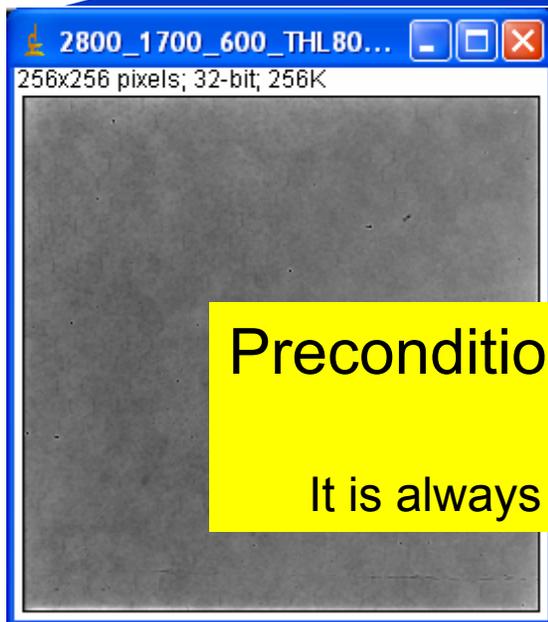


Normalized by initial flat field

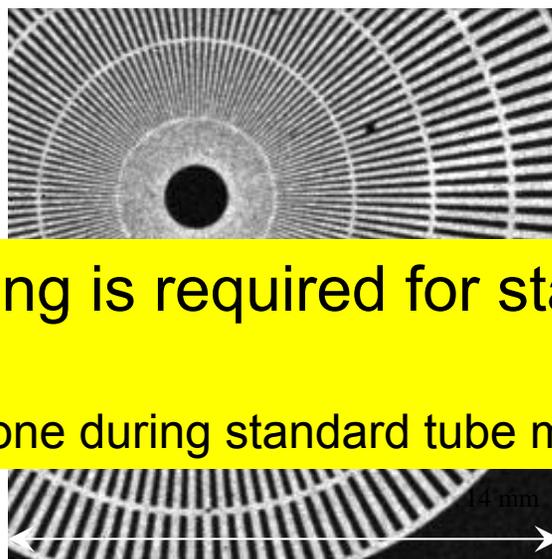
No preconditioning of the detector was performed



MCP gain reduction effect: ageing under irradiation



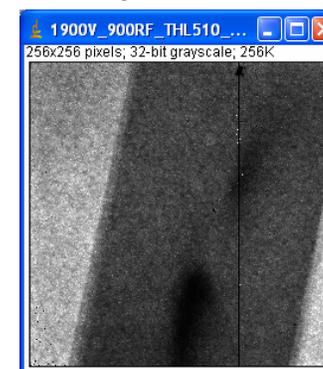
Uniform flat field
image (neutrons)



Resolution mask image
Gain $\sim 10^5$
Rate $\sim 3 \text{ MHz/cm}^2$
Accumulated dose
 $\sim 0.001 \text{ C/cm}^2$



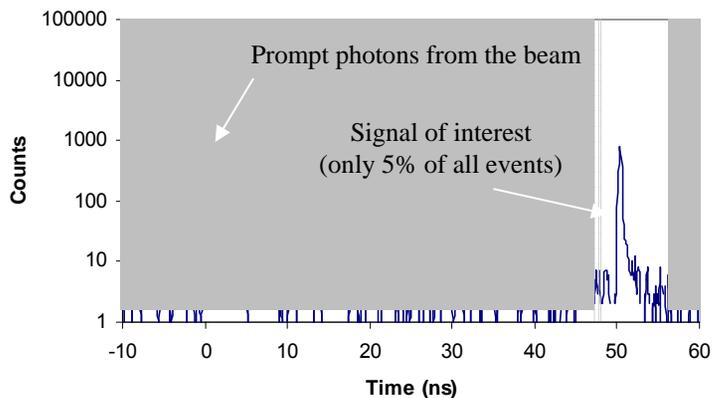
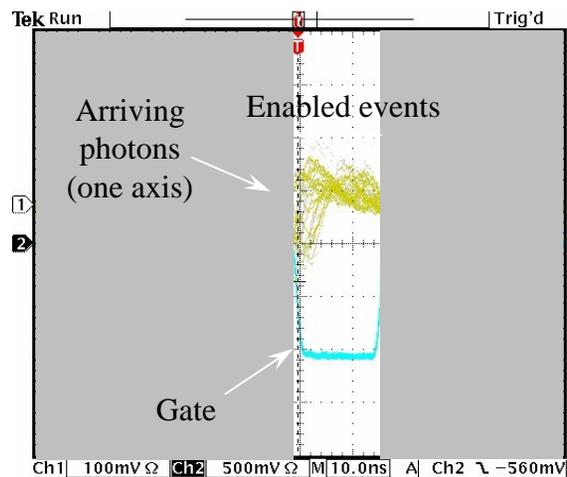
Almost uniform
flat field illumination
UV photons



No preconditioning of the detector was performed



Optimization of counting rate



Timing histogram of detected photons.
Secondary peak (~50 ns delayed) seen.

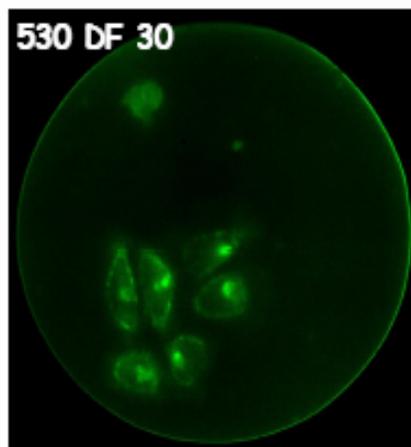


Only portion of image is enabled.
The rest of events are ignored.

A. S. Tremsin, et al., Nucl. Instr. Meth. A 582 (2007) 168.

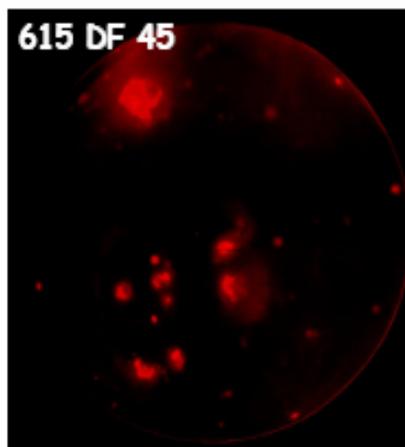


Bioimaging applications (FRET, FLIM, etc)



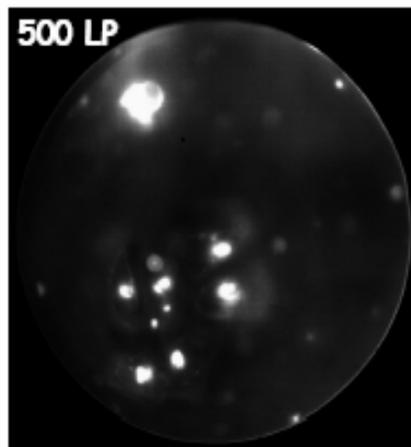
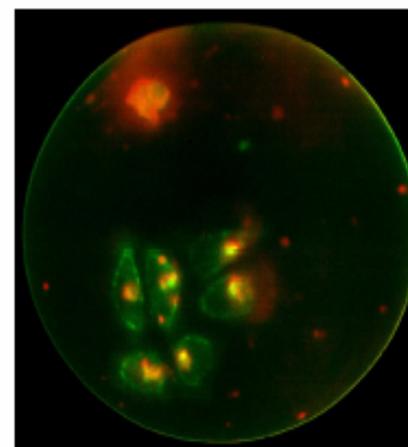
530 DF 30

[8M, 9.8 min]



615 DF 45

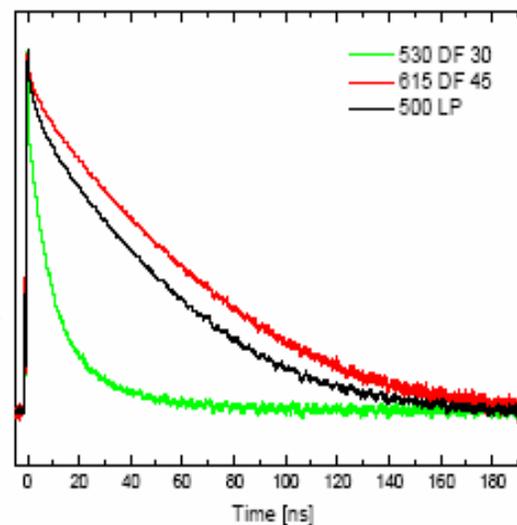
[20M, 4.1 min]



500 LP

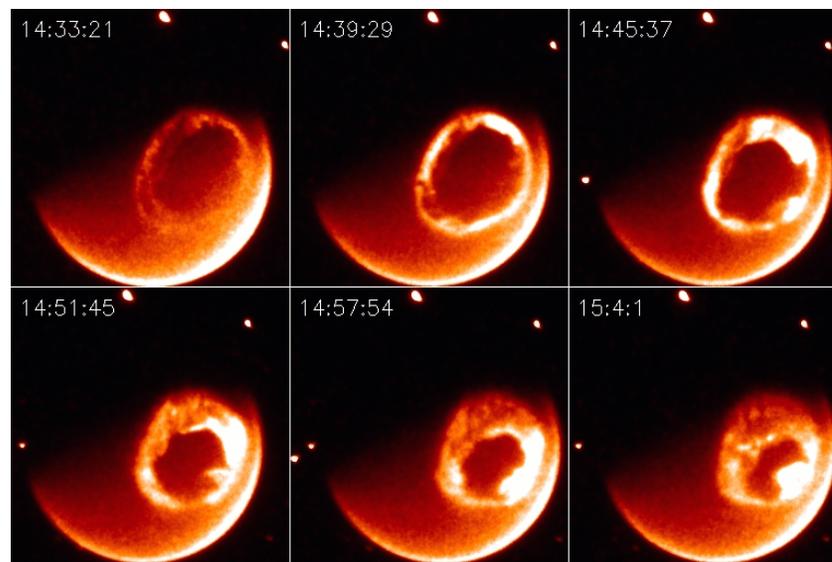
[61M, 6.3 min]

whole image
normalized
lifetime histograms





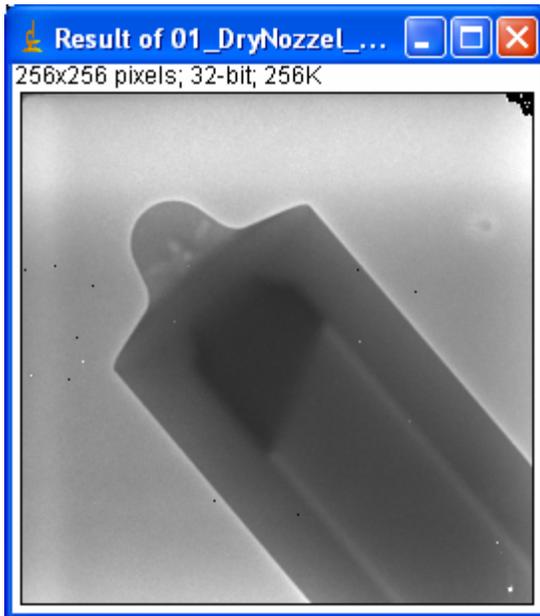
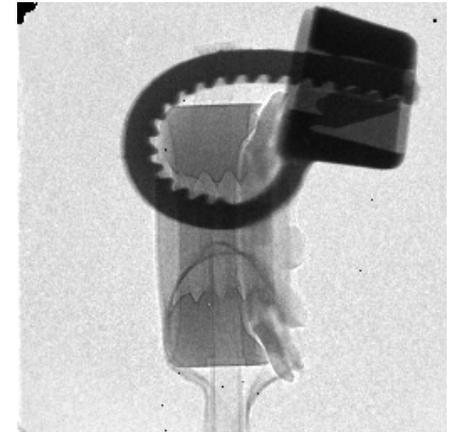
Astrophysics and Earth observing missions



[ImageWIC1](#)



Other applications: neutron imaging

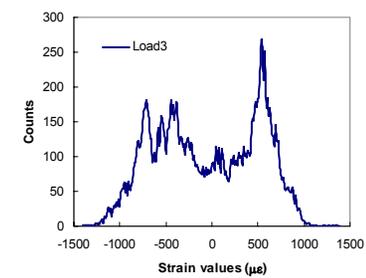
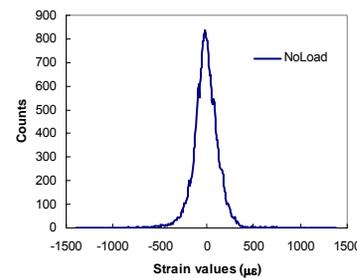
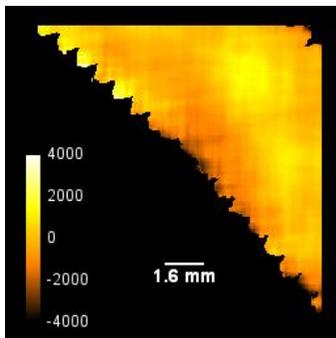
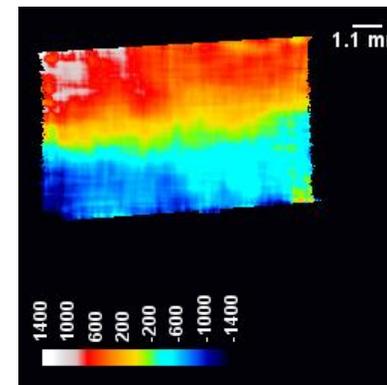
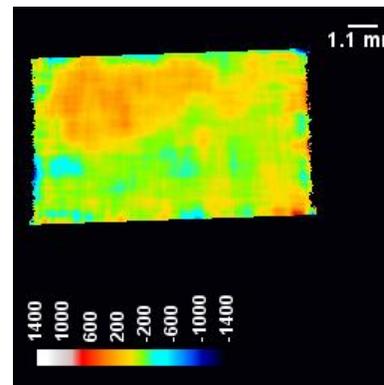
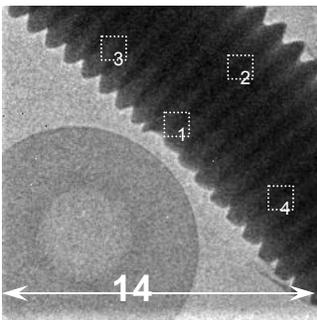
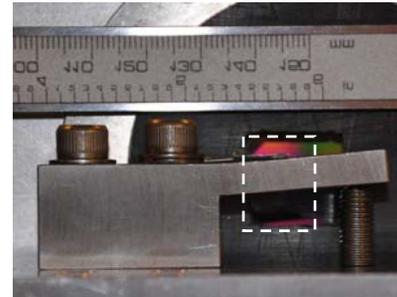
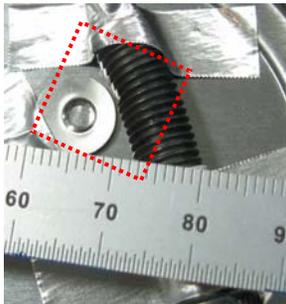


In collaboration with Nova Scientific, Inc. Sturbridge, MA,

SLAC, December 9, 2009



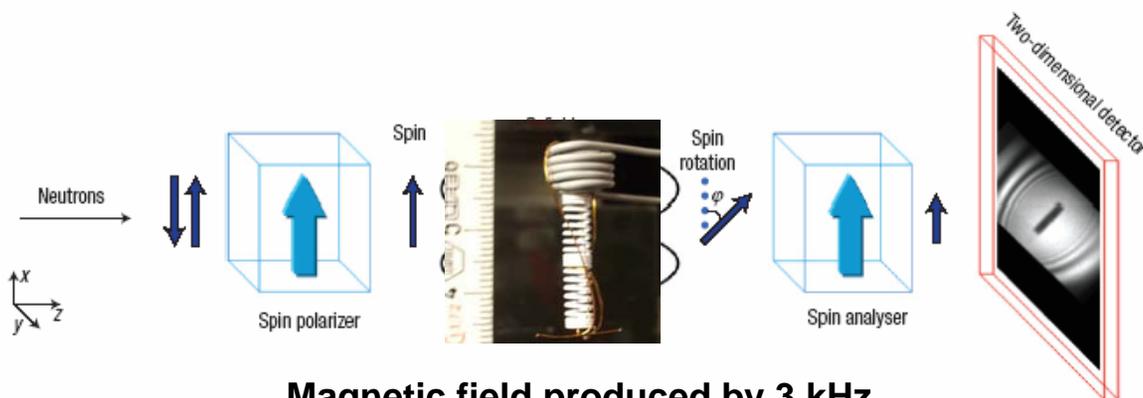
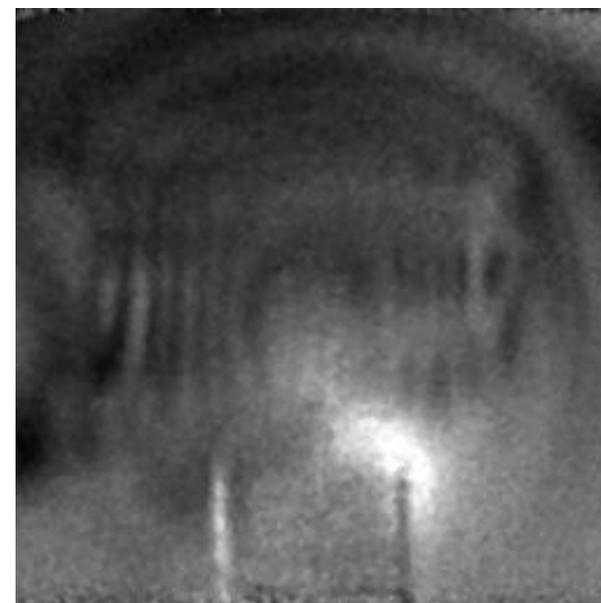
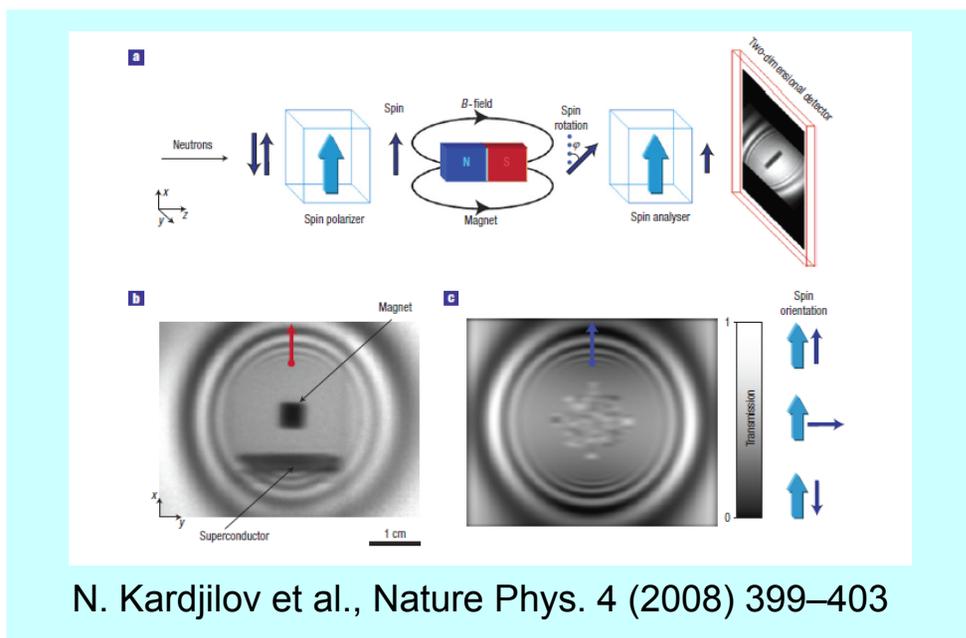
Other applications: strain mapping



In collaboration with Nova Scientific, Inc. Sturbridge, MA,



Other applications: magnetic field imaging



Magnetic field produced by 3 kHz AC current in a coil imaged

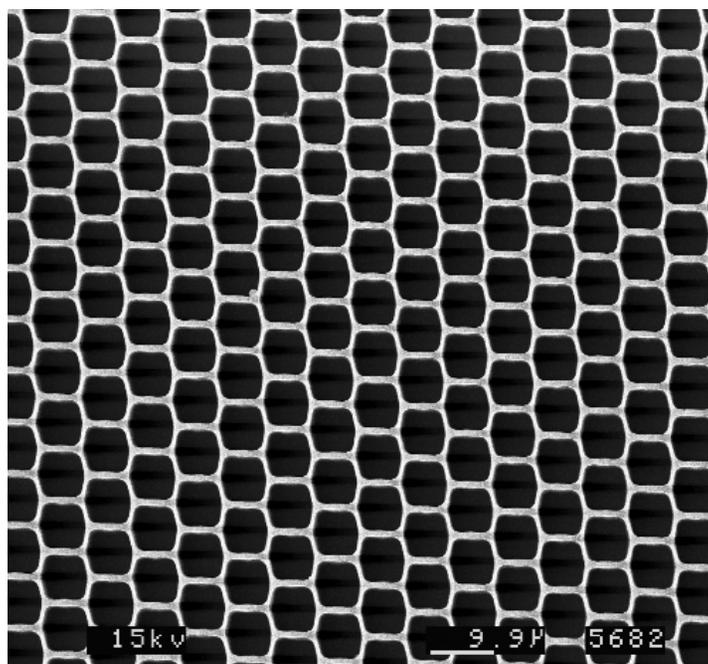


Possible MCP improvements

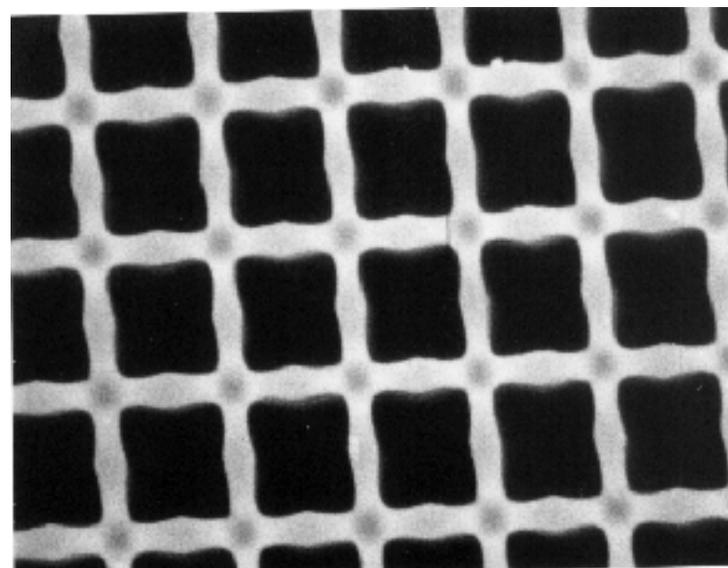
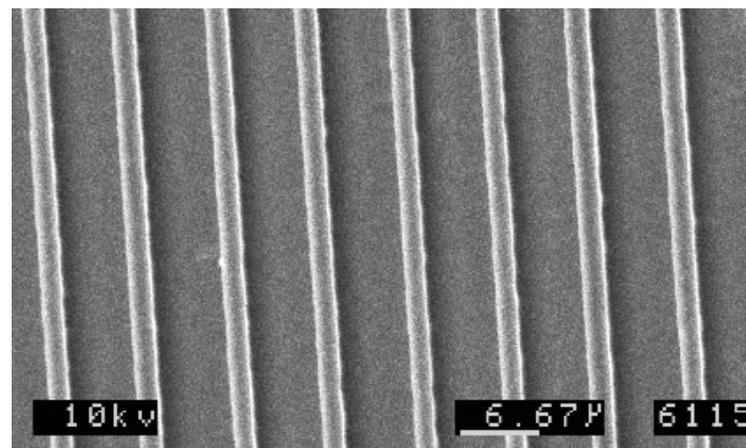
- Novel MCP substrates (micromachined)
- Increased lifetime
- Engineered conduction and emission layers
- Controlled saturation and resistance profile (higher dynamic range by offset of saturation to higher input currents)
- Better uniformity / spatial resolution
- Novel photocathode materials / opaque mode / photocathode
- Withstand much higher processing temperature
- Very Low noise



Silicon MCP Geometry



Top view of a hexagonal pore MCP with $\sim 7\mu\text{m}$ pores showing $>75\%$ open area



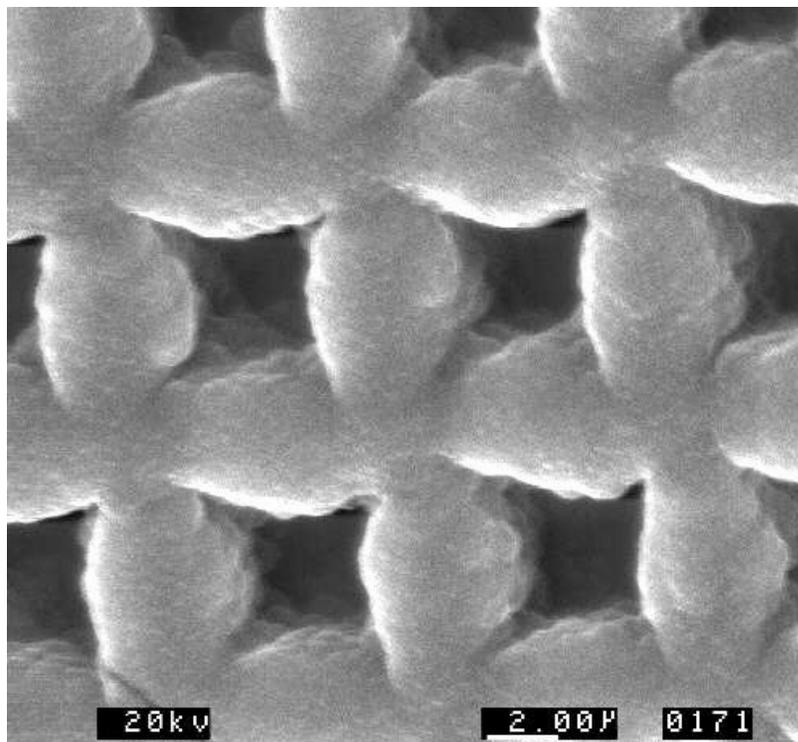
Square pore MCP

2 kx

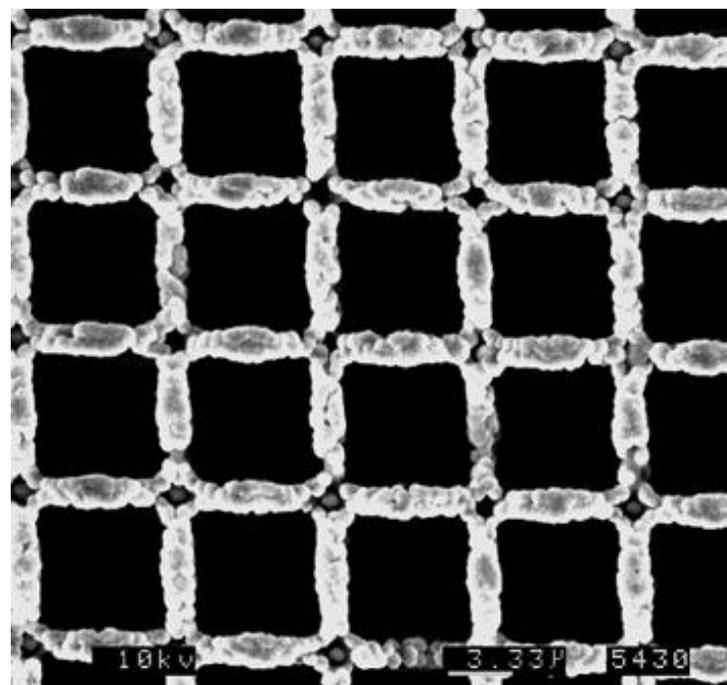
6 μm



Diamond photocathode on Si MCP



Small grain polycrystalline
diamond photocathode

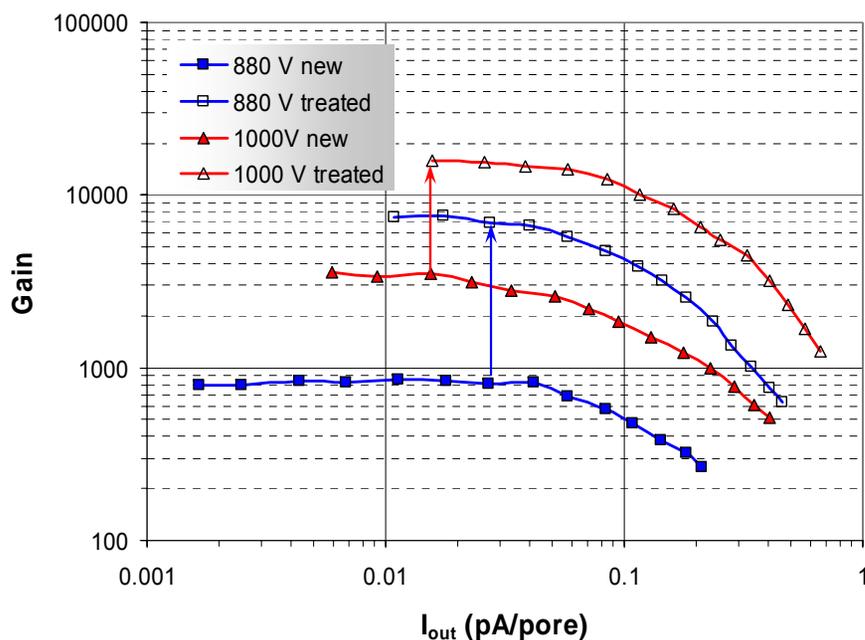


Larger grain
diamond photocathode

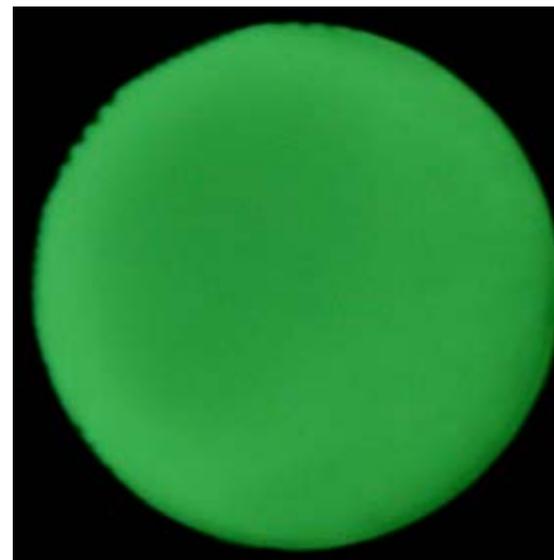


MCPs with nano-engineered films

Applied over commercial glass MCPs:
50:1 L/D, 4.8 μm pores, $\sim 250 \text{ M}\Omega$ resistance



5x-10x gain increase



Photograph of the phosphor screen.

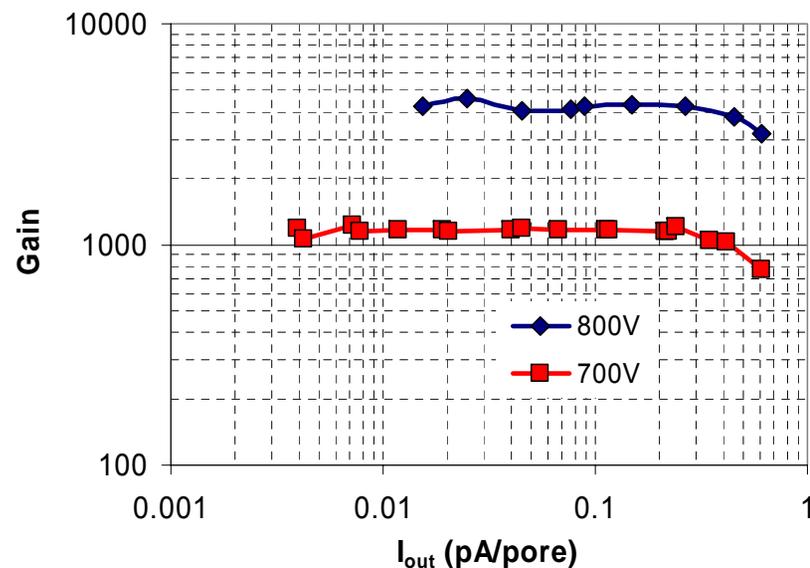
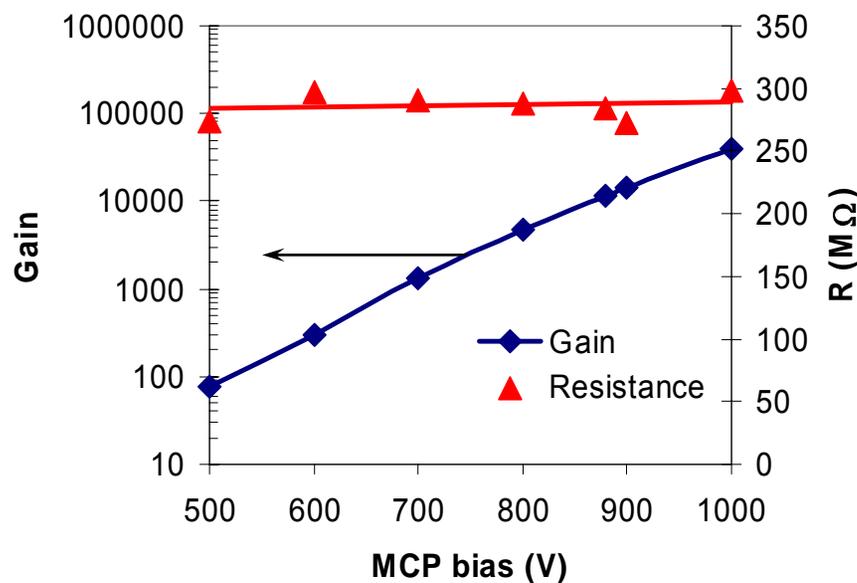
Full field illumination image.

MCP is irradiated by a uniform electron flux.



Nano-engineered conduction and emission films

10 μm pore NO LEAD glass substrate, 40:1 L/D, $R \sim 280 \text{ M}\Omega$, gain under electron bombardment



- Stable resistance
- Typical exponential gain increase with bias
- Good gain ~ 40000 at 1000V bias
- Good TCR (comparable to glass MCP values)

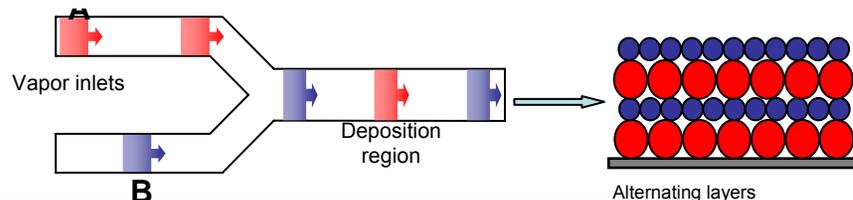
D. R. Beaulieu, et al., Nucl. Instr. Meth. A 607 (2009) 81.

Arradiance, Inc, Sudbury, MA

SLAC, December 9, 2009



ALD MCP Technology

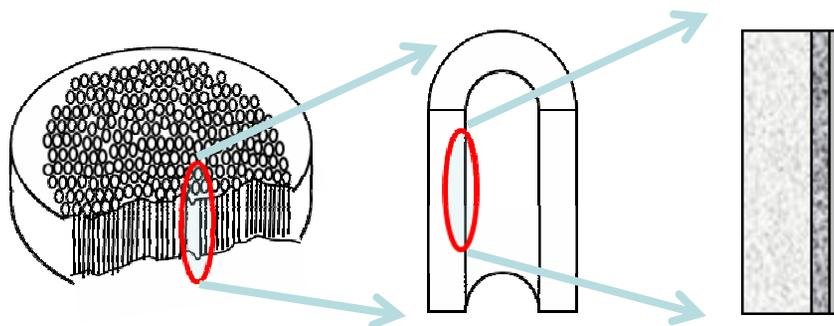


- MCP performance tied to glass composition

ALD:

- Device optimization is de-coupled from substrate.
- Semiconductor processes & process control.
- Materials engineering at the nanoscale
- Functional films composed of abundant, non-toxic materials.
- Advantages:
 - High conformality (>500:1)
 - Scalable to large areas
 - Digital thickness control
 - Pure films
 - Control over film composition
 - Low deposition temperatures (50-300°C)

- Thin film growth that relies on self-limiting surface reactions
- Gas A reacts with a surface
 - excess precursor & reaction by-product removed.
- Gas B is introduced to the evacuated chamber – reacts with surface bound A
 - excess precursor & reaction by-product removed.
- Repetition of A – B pulse sequence to build film layer-by-layer



Arradiance, Inc, Sudbury, MA